

PARA LIGHT ELECTRONICS CO., LTD.

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DATA SHEET

PART NO.: L-C192JYCT-U1

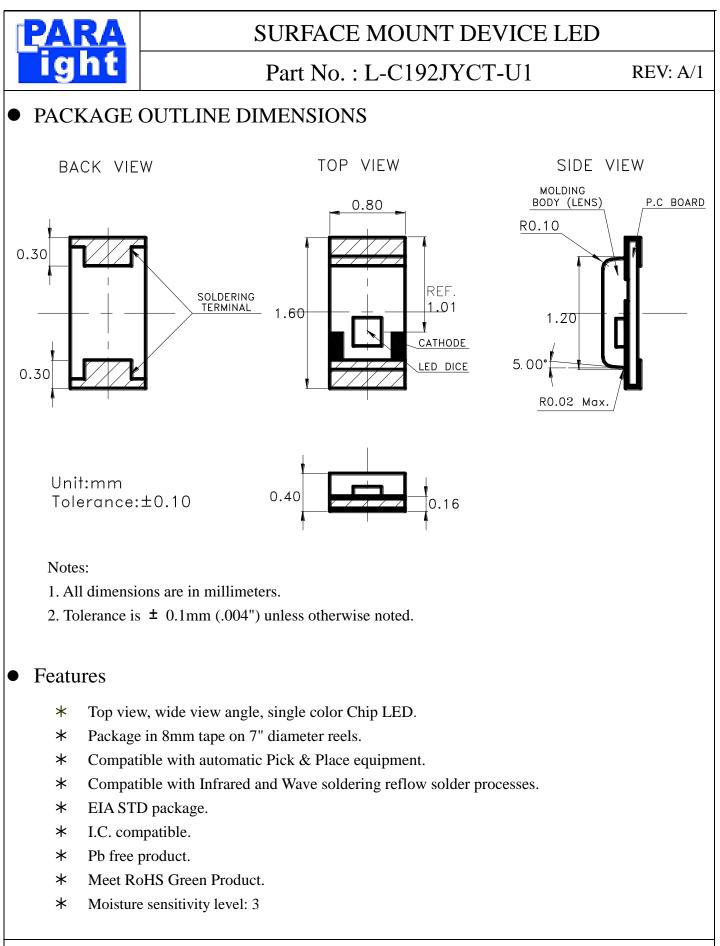
REV: <u>A/1</u>

CUSTOMER'S APPROVAL : _____ DRAWING NO. : DS-75-21-0002G

DATE : 2021-11-13

DCC : _____ Page

1



DRAWING NO. : DS-75-21-0002G

DATE : 2021-11-13 PAGE 2 of 12



Part No. : L-C192JYCT-U1

REV: A/1

• CHIP MATERIALS

- * Dice Material : AlInGaP
- * Light Color : Yellow
- * Lens Color : Water Clear

• Absolute Maximum Ratings(Ta=25°C)

Symbol	Parameter	Rating	Unit
PD	Power Dissipation	75	mW
Ipf	Peak Forward Current	80 m/	
IPF	(1/10 Duty Cycle, 0.1ms Pulse Width)	00	ША
IF	Continuous Forward Current	30	mA
VR	Reverse Voltage	5	V
Topr	Operating Temperature Range	-40 ~ +85	°C
Tstg	Storage Tem erature Range	-40 ~ +85	°C

• Electro-Optical Characteristics(Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Test Condition
Luminous Intensity	IV	40	80	180	mcd	IF=20mA
Viewing Angle	2 0 1/2		130		deg	Note 2
Peak Emission			592			Measurement
Wavelength	λp		392		nm	@Peak
Dominant Wavelength	λd	587	590	597	nm	IF=20mA
Spectral Line	Δλ		20			
Half-Width	ΔN		20		nm	
Forward Voltage	VF	1.9	2.05	2.4	V	IF =20mA
Reverse Current	IR			10	μA	VR = 5V

DRAWING NO. : DS-75-21-0002G

DATE : 2021-11-13 PAGE 3 of 12



Part No. : L-C192JYCT-U1

REV: A/1

• Bin Code List

Luminous Intensity(IV), Unit:mcd@20mA				
Bin Code	Min	Max		
R1	40	60		
R2	60	90		
S 1	90	130		
S2	130	180		

Forward Voltage(VF), Unit:V@20mA				
Bin Code	Min	Max		
4	1.9	2.0		
5	2.0	2.1		
6	2.1	2.2		
7	2.2	2.3		
8	2.3	2.4		

Tolerance of each bin are $\pm 15\%$

Tolerance of each bin are ± 0.1 Volt

Dominant Wavelength (Hue), Unit: nm@20mA				
Bin Code	Min	Max		
YA01	587.0	589.0		
YA02	589.0	591.0		
YB01	591.0	593.0		
YB02	593.0	595.0		
YC01	595.0	597.0		

Tolerance of each bin are ± 0.5 nm

Notes:

- 1. Luminous intensity is measured with a light sensor and filter combination that proximities the CIE eye-response curve.
- 2. θ 1/2 is the off-axis angle at which the luminous intensity is half the axial luminous intensity.
- 3. Caution in ESD :

Static Electricity and surge damages the LED. It is recommended use a wrist band or anti-electrostatic glove when handling the LED. All devices, equipment and machinery must be properly grounded.

DRAWING NO. : DS-75-21-0002G

DATE : 2021-11-13 PAGE

4 of 12



Part No. : L-C192JYCT-U1

REV: A/1

• Typical Electro-Optical Characteristics Curves

(25°CAmbient Temperature Unless Otherwise Noted)

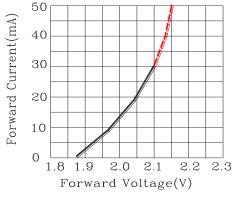


Fig.2 Forward Current vs.Forward Voltage

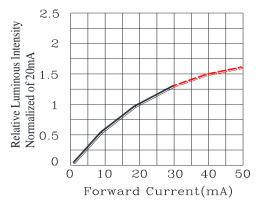


Fig.4 Relative Luminous Intensity vs.Forward Current

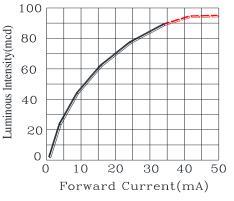


Fig.3 Luminous Intensity vs.Forward Current

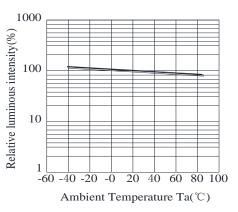
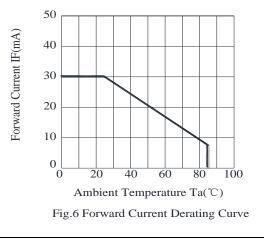
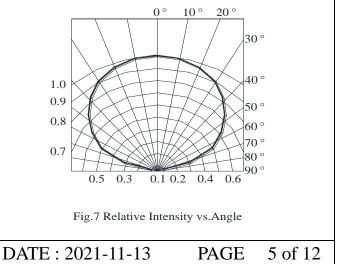


Fig.5 Luminous Intensity vs.Ambient Temperature



DRAWING NO. : DS-75-21-0002G





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REV: A/1

• Label Explanation



В С Е F Α D A---EM: Emos Code B---S:SMD L---Local D----Year E---Month F---SPEC. PACKING QUANTITY OF BAG: 3000pcs for 150, 170, 110, 155, 115 series 4000pcs for 191 series 5000pcs for 192 series DATE CODE: <u>2012</u> <u>09</u> 10 G Η Ι

G--- Year H--- Month

I --- Day

DRAWING NO. : DS-75-21-0002G

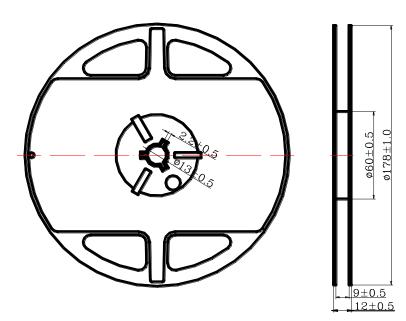
DATE : 2021-11-13 PAGE 6 of 12



Part No. : L-C192JYCT-U1

REV: A/1

• Reel Dimensions



Notes:

- 1. Taping Quantity : 5000pcs
- 2. The tolerances unless mentioned is ± 0.1 mm, Angle $\pm 0.5^{\circ}$, Unit : mm.

DATE : 2021-11-13 PAGE 7 of 12

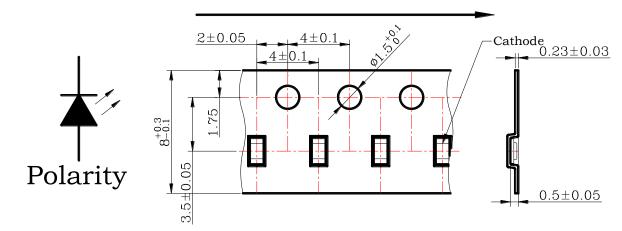


Part No. : L-C192JYCT-U1

REV: A/1

• Package Dimensions Of Tape And Reel

Progressive direction



Notes:All dimensions are in millimeters.

DRAWING NO. : DS-75-21-0002G

DATE : 2021-11-13 PAGE 8 of 12



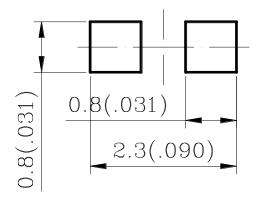
Part No. : L-C192JYCT-U1

REV: A/1

• Cleaning

- * If cleaning is required, use the following solutions for less than 1 minute and less than 40° C.
- * Appropriate chemicals: Ethyl alcohol and isopropyl alcohol.
- Effect of ultrasonic cleaning on the LED resin body differs depending on such factors as the oscillator output, size of PCB and LED mounting method. The use of ultrasonic cleaning should be enforced at proper output after confirming there is no problem.

Suggest Soldering Pad Dimensions

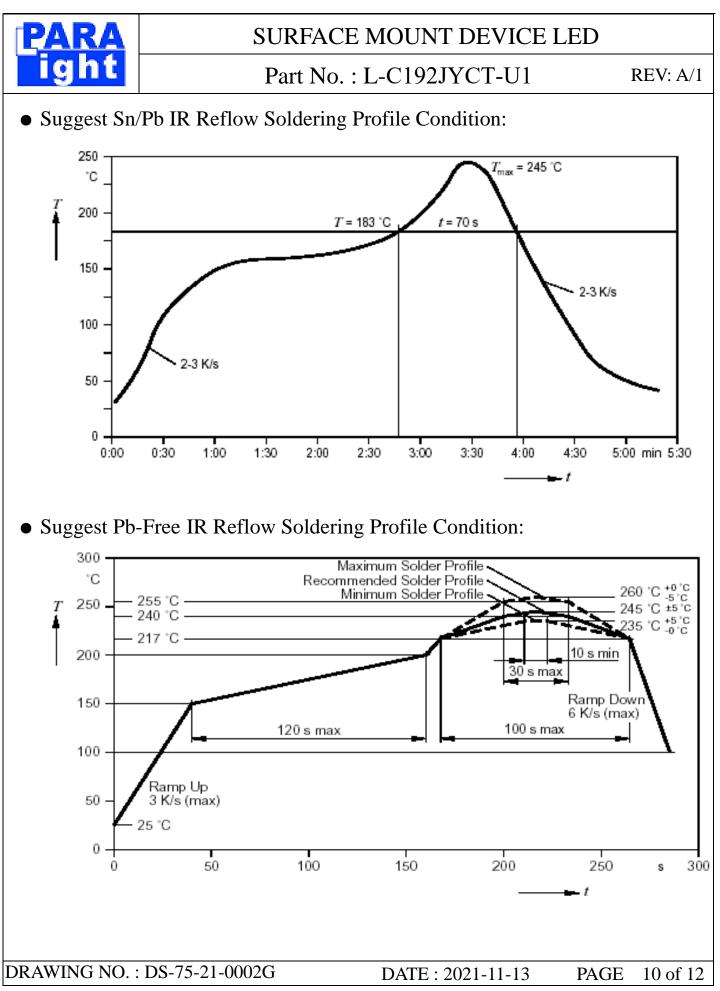


Direction of PWB camber and go to reflow furnace

DRAWING NO. : DS-75-21-0002G

DATE : 2021-11-13 PAGE 9 of 12

PARA-FOR-068





Part No. : L-C192JYCT-U1

REV: A/1

• CAUTIONS

1. Application Limitation :

The LED's described here are intended to be used for ordinary electronic equipment (such as office equipment, communication equipment and household application).Consult PARA's sales in advance for information on application in which exceptional quality and reliability are required, particularly when the failure or malfunction of the LED's may directly jeopardize life or health (such as airplanes, automobiles, traffic control equipment, life support system and safety devices).

2.Storage :

Do not open moisture proof bag before the products are ready to use.

Before opening the package: The LEDs should be kept at 30° C or less and 90% RH or less.

If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment: 60 ± 5 °C for 24 hours.

3.Soldering

Do not apply any stress to the lead frame during soldering while the LED is at high temperature. Recommended soldering condition.

Reflow Soldering :

Pre-heat 120~150 °C, 120sec. MAX., Peak temperature : 240 °C Max. Soldering time : 10 sec Max. Soldering Iron : (Not recommended)

Temperature 300 $^{\circ}$ C Max., Soldering time : 3 sec. Max.(one time only), power dissipation of iron : 20W Max. use SN60 solder of solder with silver content and don't to touch LED lens when soldering. Wave soldering :

Pre-heat 100 $^{\circ}$ Max, Pre-heat time 60 sec. Max, Solder wave 260 $^{\circ}$ Max, Soldering time 5 sec. Max. performed consecutively cooling process is required between 1st and 2nd soldering processes.



Part No. : L-C192JYCT-U1

REV: A/1

4. Lead-Free Soldering

For Reflow Soldering :

- 1、 Pre-Heat Temp: 150-180°C,120sec.Max.
- 2. Soldering Temp: Temperature Of Soldering Pot Over 230°C,40sec.Max.
- 3、Peak Temperature: 260°C, 5sec.
- 4. Reflow Repetition: 2 Times Max.
- 5. Suggest Solder Paste Formula : 93.3 Sn/3.1 Ag/3.1 Bi/0.5 Cu

For Soldering Iron (Not Recommended) :

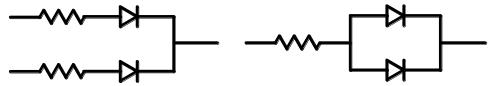
- 1. Iron Tip Temp: 350°C Max.
- 2. Soldering Iron: 30w Max.
- 3. Soldering Time: 3 Sec. Max. One Time.

For Dip Soldering :

- 1. Pre-Heat Temp: 150°C Max. 120 Sec. Max.
- 2、Bath Temp: 265°C Max.
- 3、 Dip Time: 5 Sec. Max.
- 5. Drive Method

Circuit model A

Circuit model B



(A)Recommended circuit.

(B)The difference of brightness between LED's could be found due to the Vf-If characteristics of LED.